

6.7 TFBGA100 package information (A08Q)

This TFBGA is a 100-ball, 8 x 8 mm, 0.8 mm pitch fine pitch ball grid array package.

Figure 65. TFBGA100 - Outline

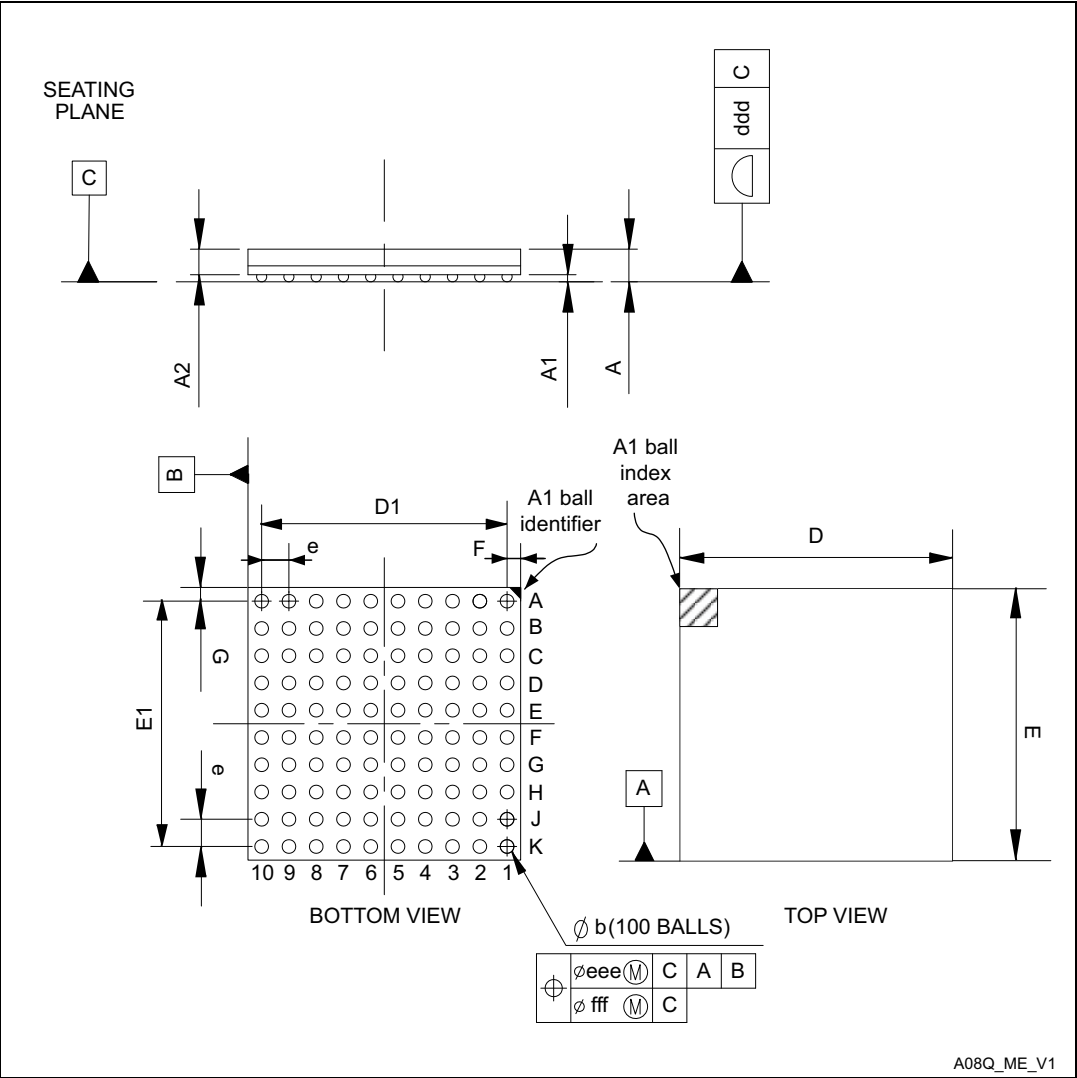


Table 112. TFBGA100 - Mechanical data

Symbol	millimeters			inches ⁽¹⁾		
	Min	Typ	Max	Min	Typ	Max
A	-	-	1.100	-	-	0.0433
A1	0.150	-	-	0.0059	-	-
A2	-	0.760	-	-	0.0299	-
b	0.350	0.400	0.450	0.0138	0.0157	0.0177
D	7.850	8.000	8.150	0.3091	0.3150	0.3209
D1	-	7.200	-	-	0.2835	-
E	7.850	8.000	8.150	0.3091	0.3150	0.3209
E1	-	7.200	-	-	0.2835	-
e	-	0.800	-	-	0.0315	-
F	-	0.400	-	-	0.0157	-
G	-	0.400	-	-	0.0157	-
ddd	-	-	0.100	-	-	0.0039
eee	-	-	0.150	-	-	0.0059
fff	-	-	0.080	-	-	0.0031

1. Values in inches are converted from mm and rounded to 4 decimal digits.

Figure 66. TFBGA100 - Footprint example

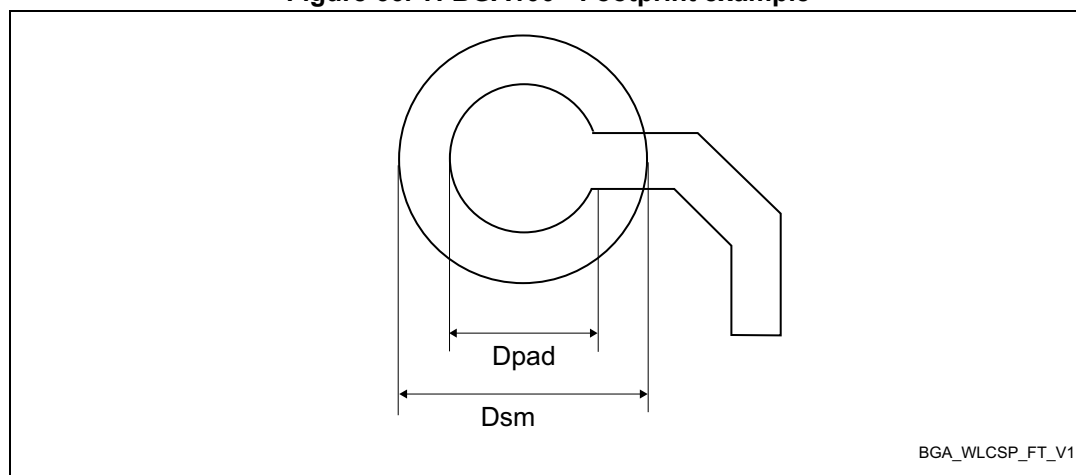


Table 113. TFBGA100 - Example of PCB design rules

Dimension	Recommended values
Pitch	0.8
Dpad	0.400 mm
Dsm	0.470 mm typ. (depends on the soldermask registration tolerance)

Table 113. TFBGA100 - Example of PCB design rules (continued)

Dimension	Recommended values
Stencil opening	0.400 mm
Stencil thickness	Between 0.100 mm and 0.125 mm
Pad trace width	0.120 mm